EMI Filter with ESD Protection for Data Line Applications

Product Description

The CM6317 is an 18-bump EMI filter with ESD protection device for data line application in a 0.4 mm pitch, 5 x 4 CSP form factor. It is fully compliant with IEC 61000-4-2. The CM6317 is RoHS II compliant.

Features

- 18-Bump, 1.96 mm X 1.56 mm Footprint Chip Scale Package
- These Devices are Pb-Free and are RoHS Compliant



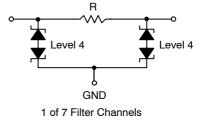
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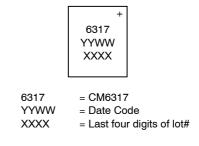


WLCSP18 CASE 567CG





MARKING DIAGRAM



ORDERING INFORMATION

Device	Package	Shipping [†]
CM6317	CSP-18 (Pb-Free)	5000/Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

CM6317

PACKAGE / PINOUT DIAGRAMS

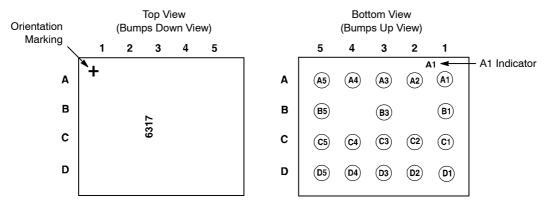


Table 1. PIN DESCRIPTIONS

A5 = Line 1	A4 = Line 2	A3 = GND	A2 = Line 1	A1 = Line 2
B5 = Line 3		B3 = GND		B1 = Line 3
C5 = Line 4	C4 = Line 5	C3 = GND	C2 = Line 4	C1 = Line 5
D5 = Line 6	D4 = Line 7	D3 = GND	D2 = Line 6	D1 = Line 7

ELECTRICAL SPECIFICATIONS AND CONDITIONS

Table 2. PARAMETERS AND OPERATING CONDITIONS

Parameter	Rating	Units
Storage Temperature Range	-55 to +150	°C
Operating Temperature Range	ture Range -40 to +85	
Power Dissipation at 70°C per Channel	60	mW

Table 3. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

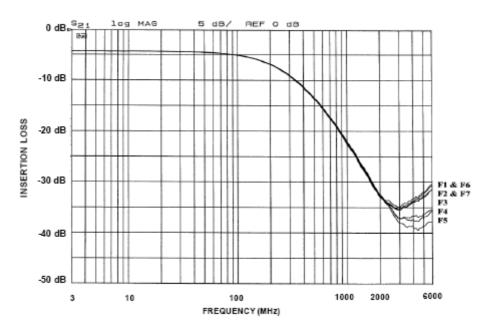
Symbol	Parameter	Conditions	Min	Тур	Max	Units
R	Resistance		56	70	84	Ω
С	Capacitance per Line	At 1 MHz, V _{IN} = 0 V			30	pF
V _{BR}	Breakdown Voltage	$I_{R} = \pm 1 \text{ mA}$	±6	±7.8	±10	V
I _{LEAK}	Leakage Current per Channel	V _{IN} = 3.0 V		10	100	nA
V _{ESD}	ESD Protection Peak Discharge Voltage a) Contact Discharge per IEC 61000-4-2 standard b) Air Discharge per IEC 61000-4-2 standard	(Note 2)	±14 ±15			kV

1. All parameters specified at $T_A = 25^{\circ}C$ unless otherwise noted. 2. Standard IEC 61000–4–2 with $C_{Discharge} = 150 \text{ pF}$, $R_{Discharge} = 330 \Omega$.

CM6317

RF CHARACTERISTICS

T_{A} = 25°C, DC Bias = 0 V, 50 Ω Environment

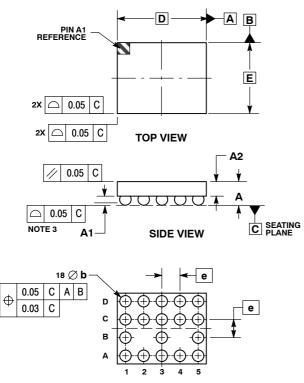




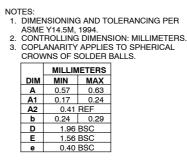
CM6317

PACKAGE DIMENSIONS

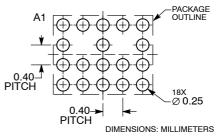
WLCSP18, 1.96x1.56 CASE 567CG-01 ISSUE O



BOTTOM VIEW



RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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